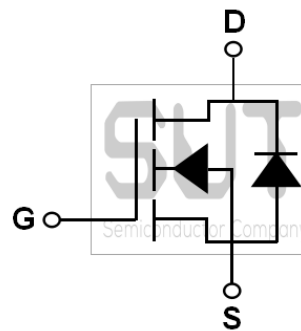


N-Channel 100-V_(D-S) SGT MOSFET

PRODUCT SUMMARY		
B _{VDSS} (V)	R _{DS(on)} (mΩ)(MAX)	I _D (A)
100	13.5@V _{GS} =10V	50

PPAK5X6 Pin Configuration



ABSOLUTE MAXIMUM RATINGS(T_C=25°C UNLESS OTHERWISE NOTED)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _{GS}	+20/-12	V
Drain Current-Continuous (T _C =25°C)	I _D	50	A
Drain Current-Continuous (T _C =100°C)		32	A
Drain Current-Pulsed ¹	I _{DM}	200	A
Single Pulse Avalanche Energy ²	EAS	115	mJ
Single Pulse Avalanche Current ²	IAS	48	A
Power Dissipation (T _C =25°C)	P _D	98	W
Power Dissipation-Derate above 25°C		0.79	W/°C
Storage Temperature Range	T _{STG}	-50 to 150	°C
Operating Junction Temperature Range	T _J	-50 to 150	°C

THERMAL CHARACTERISTICS

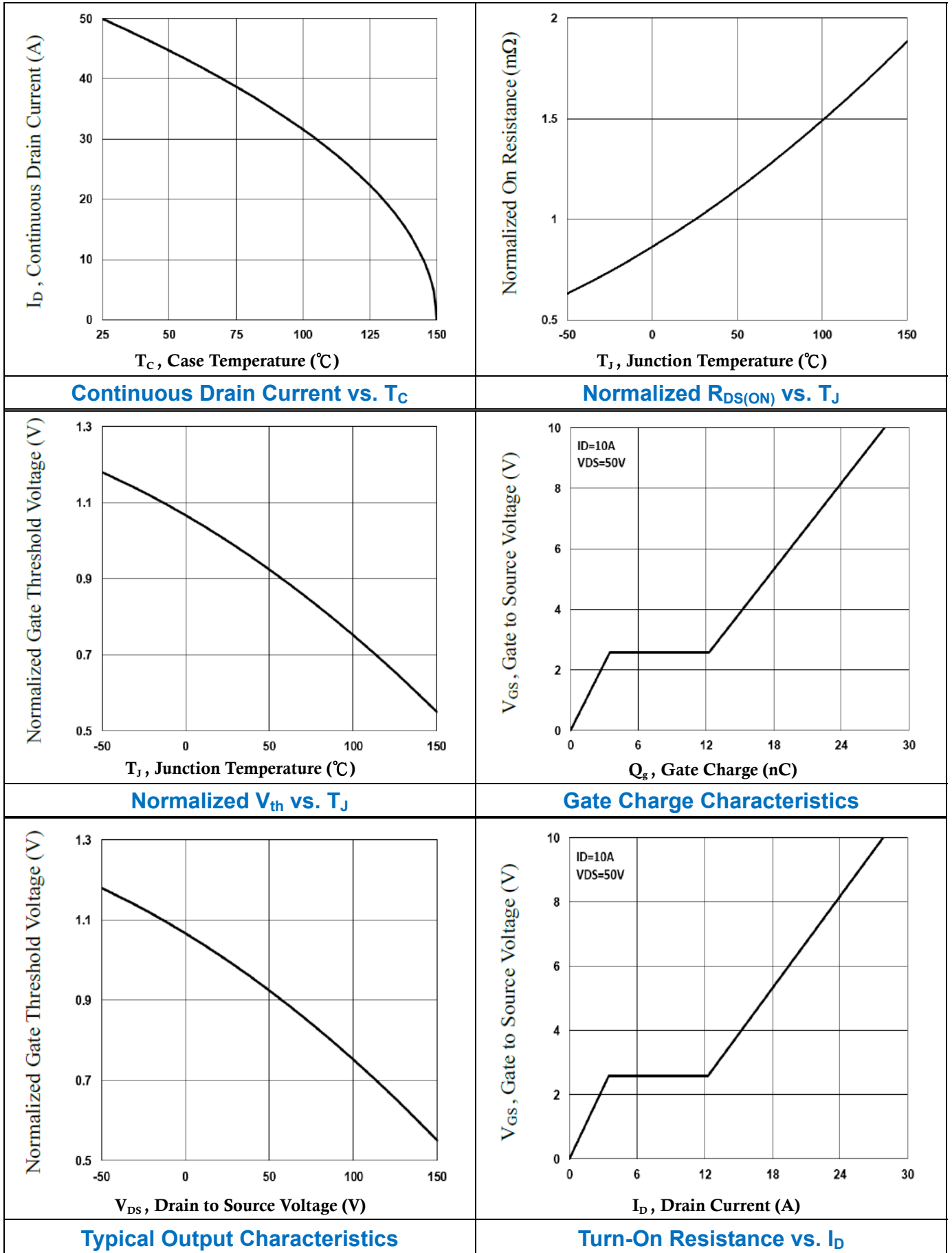
Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance Junction to ambient	R _{θJA}	---	62	°C/W
Thermal Resistance Junction to Case	R _{θJC}	---	1.27	°C/W

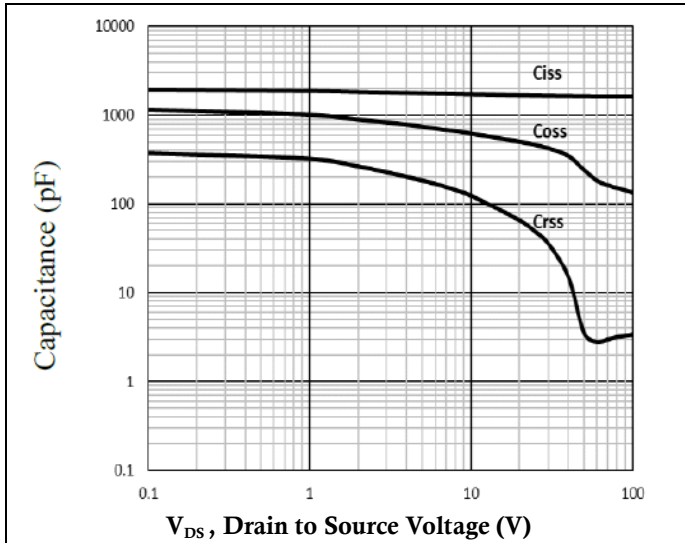
ELECTRICAL CHARACTERISTICS (T _J =25°C UNLESS OTHERWISE NOTED)						
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	100	---	---	V
BV _{DSS} Temperature Coefficient	ΔBV _{DSS} /ΔT _J	Reference to 25°C, I _D =1mA	---	0.06	---	V/°C
Drain-Source Leakage Current	I _{DSS}	V _{GS} =0V, V _{DS} =100V, T _J =25°C	---	---	1	uA
		V _{GS} =0V, V _{DS} =80V, T _J =125°C	---	---	10	uA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =20V, V _{DS} =0V	---	---	±100	nA
On Characteristics						
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =25A	---	11	13.5	mΩ
		V _{GS} =10V, I _D =25A(T _J =125°C)	---	18.5	---	mΩ
		V _{GS} =4.5V, I _D =20A	---	15.9	21	mΩ
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =250uA	1.0	1.5	2.5	V
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)}		---	-5.1	---	mV/°C
Forward Transconductance	g _{fs}	V _{DS} =10V, I _D =2A	---	10	---	S
Dynamic and Switching Characteristics						
Total Gate Charge ^{3, 4}	Q _g	V _{GS} =10V, V _{DS} =50V, I _D =10A	---	27.8	55	nC
Gate-Source Charge ^{3, 4}	Q _{gs}		---	3.5	7.0	
Gate-Drain Charge ^{3, 4}	Q _{gd}		---	8.8	17	
Turn-On Delay Time ^{3, 4}	T _{d(on)}	V _{GS} =10V, V _{DD} =50V, R _G =6Ω, I _D =1A	---	14.2	28	ns
Rise Time ^{3, 4}	T _r		---	20.8	42	
Turn-Off Delay Time ^{3, 4}	T _{d(off)}		---	42	84	
Fall Time ^{3, 4}	T _f		---	30	60	
Input Capacitance	C _{iss}	V _{GS} =0V, V _{DS} =50V, F=1MHz	---	1640	3280	pF
Output Capacitance	C _{oss}		---	240	480	
Reverse Transfer Capacitance	C _{rss}		---	4.0	10	
Gate resistance	R _g	V _{GS} =0V, V _{DS} =0V, F=1MHz	---	1.14	---	Ω
Drain-Source Diode Characteristics and Maximum Ratings						
Continuous Source Current	I _S	V _G =V _D =0V, Force Current	---	---	50	A
Pulsed Source Current	I _{SM}		---	---	100	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =1A, T _J =25°C	---	---	1.0	V
Reverse Recovery Time ³	t _{rr}	V _{GS} =0V, I _S =10A,	---	43.5	---	ns
Reverse Recovery Charge ³	Q _{rr}	dI/dt=100A/μs, T _J =25°C	---	59.6	---	nC

Note :

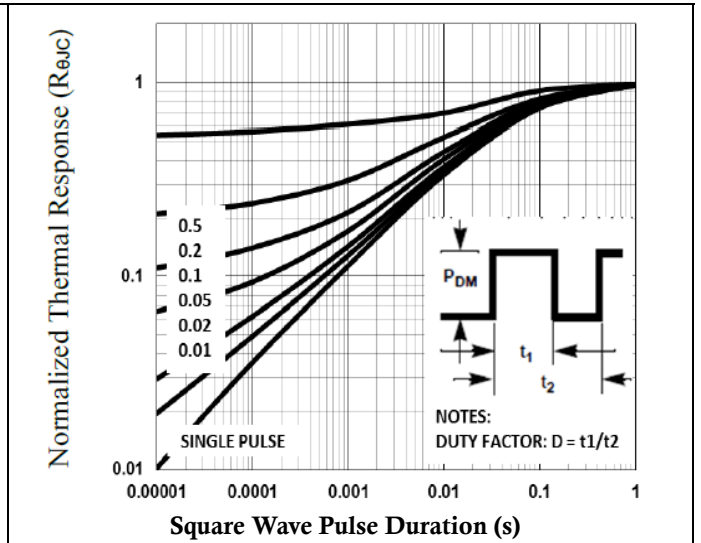
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V_{GS}=10V, V_{DD}=50V, L=0.1mH, I_{AS}=48A, R_G=25Ω, Starting T_J=25°C.
3. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
4. Essentially independent of operating temperature.

100V N-Channel MOSFETs

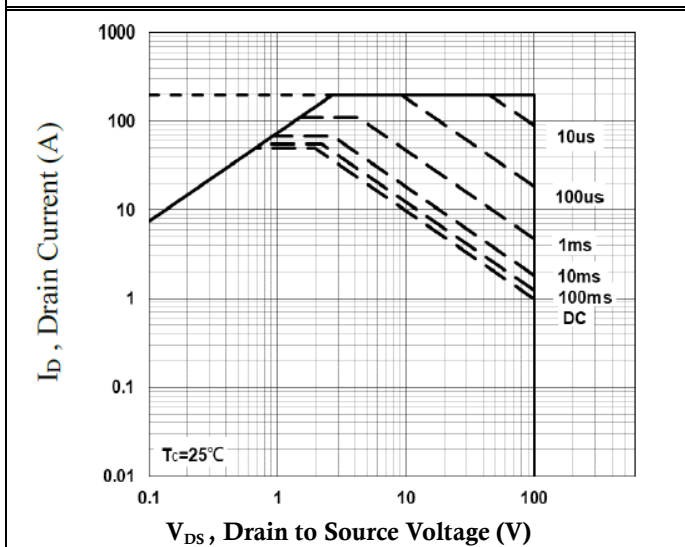




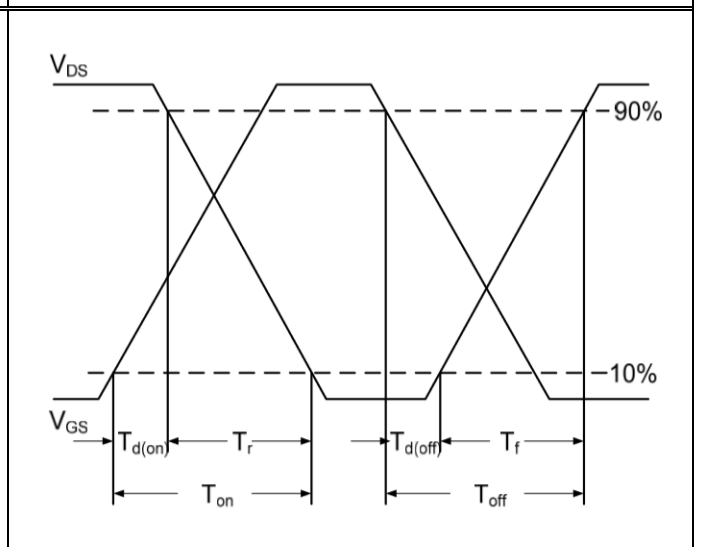
Capacitance Characteristics



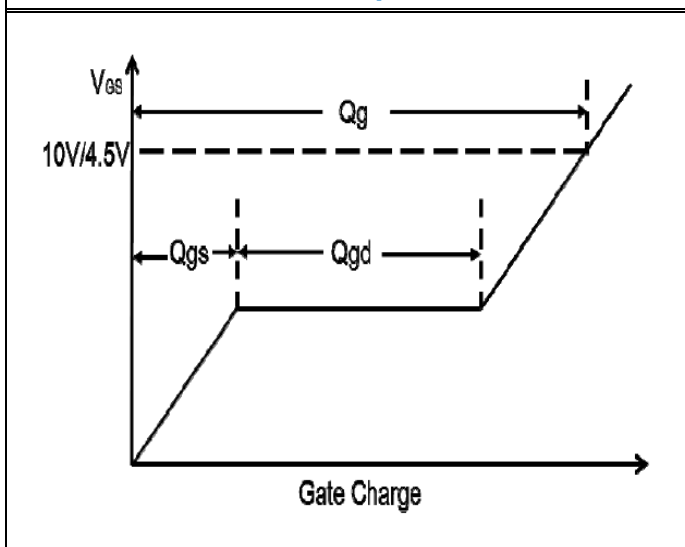
Normalized Transient Impedance



Maximum Safe Operation Area

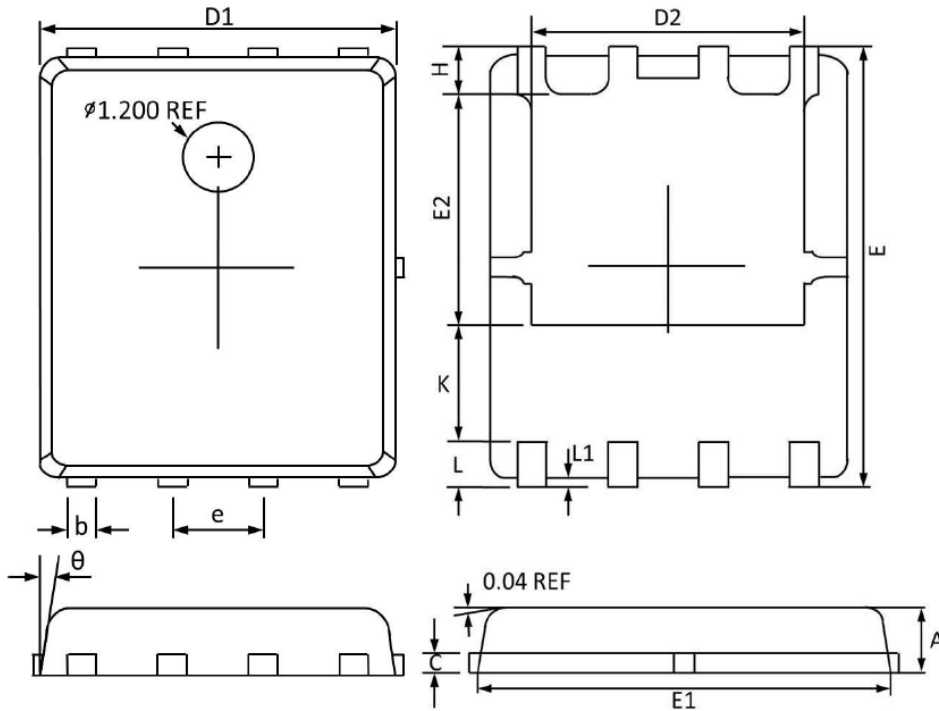


Switching Time Waveform



Gate Charge Waveform

PPAK5X6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.100	0.800	0.043	0.031
b	0.510	0.330	0.020	0.013
C	0.300	0.200	0.012	0.008
D1	5.100	4.800	0.201	0.189
D2	4.100	3.610	0.161	0.142
E	6.200	5.900	0.244	0.232
E1	5.900	5.700	0.232	0.224
E2	3.780	3.350	0.149	0.132
e	1.270(BSC)		0.050(BSC)	
H	0.700	0.410	0.028	0.016
K	1.500	1.100	0.059	0.043
L	0.710	0.510	0.028	0.020
L1	0.200	0.060	0.008	0.002
θ	12°	0°	12°	0°